

Amendments to the Claims:

The following listing will replace all prior listing of claims in the application.

Listing of Claims:

1. (Currently amended) ~~A Method~~ method of producing a complex structure, the structure being adapted to be dissociated in a separation region, the method by comprising assembling two substrates (5, 6; 11, 13) at respective connecting faces thereof, the structure being adapted to be dissociated in a separation region, wherein characterized in that, prior to assembly, a tangential stress state difference is created between the ~~two~~ connecting faces ~~to be assembled by applying mechanical forces curving to curve~~ each of the two substrates ~~to be assembled by applying mechanical forces, this wherein the tangential stress state difference being is selected to obtain produce~~ a predetermined stress state within the ~~assembled~~ complex structure at the moment of dissociation.

2. (Currently amended) ~~The Method~~ method according to claim 1 ~~of producing a complex structure, characterized in that, wherein~~ the tangential stress state difference between the ~~two~~ connecting faces ~~to be assembled~~ is selected to minimize the stresses in the separation region at the moment of dissociation.

3. (Currently amended) ~~The Method~~ method according to claim 1 ~~or claim 2 of producing a complex structure, characterized in that further comprising curving the two substrates are curved so that the two~~ connecting faces ~~to be assembled are comprise~~ respectively concave and convex faces.

4. (Currently amended) ~~The Method~~ method according to claim 3 ~~of producing a complex structure, characterized in that, wherein curving the two substrates are curved comprises curving so that the two~~ connecting faces ~~to be assembled are comprise~~ complementary faces.

5. (Currently amended) ~~The Method~~ method according to claim 4 ~~of producing a complex structure, characterized in that, wherein curving the two substrates~~

~~are curved~~ comprises curving so that the ~~two connecting faces to be assembled~~ comprise respectively spherical concave and spherical convex faces.

6. (Currently amended) ~~The Method~~ method according to ~~any one of claims~~ claim 1 to 5 of producing a complex structure, characterized in that the wherein applying mechanical forces ~~applied to the substrate result from the creation of~~ comprises creating a pressure difference between the ~~two connecting faces of said substrate~~.

7. (Currently amended) ~~The Method~~ method according to claim 6, ~~of producing a complex structure, characterized in that the~~ wherein creating a pressure difference between the ~~two connecting faces of the substrate to be curved so that it has a concave face to be assembled is created by~~ comprises aspirating said ~~substrate~~ one of the two substrates onto a concave preform having a suitable profile selected as a function of that to be imparted and imparting the profile to the a face of the one substrate, to be assembled and on which and wherein the one substrate structure rests locally on the concave preform at its periphery.

8. (Currently amended) ~~The Method~~ method according to claim 6, ~~of producing a complex structure, characterized in that~~ wherein creating the pressure difference between the ~~connecting faces of the substrate to be curved so that it has a concave face to be assembled is created by~~ comprises aspirating said ~~substrate~~ one of the two substrates into a cavity, the one substrate resting locally at its periphery on a seal bordering the cavity.

9. (Currently amended) ~~The Method~~ method according to ~~any one of~~ claims claim 1 to 5 of producing a complex structure, characterized in that the wherein applying mechanical forces ~~applied to the substrate are the result of~~ comprises deforming one of the two substrates ~~substrate~~ between complementary first and second preforms, one of which is concave and the other of which is convex, with and imparting selected profiles selected as a function of that to be imparted to the connecting face to be assembled.

10. (Currently amended) ~~The Method~~ method according to claim 9, of producing a complex structure, characterized in that wherein the first complementary preform ~~is one of the~~ comprises the other of the two ~~one of the substrates to be assembled that has already been,~~ wherein the substrate is curved to ~~the~~ have a selected profile.

11. (Currently amended) ~~The Method~~ method according to ~~claim~~ claim 9 or claim 10 of producing a complex structure, characterized in that, wherein the second preform ~~has~~ includes aspiration channels for keeping the one substrate curved when the first preform has been removed.

12. (Currently amended) ~~The Method~~ method according to ~~any one of~~ claims claim 1, to 5 of producing a complex structure, characterized in that the wherein applying mechanical forces ~~are applied~~ comprises applying mechanical forces simultaneously to the two substrates ~~to be assembled~~ by deforming the two substrates between two preforms having selected profiles ~~selected as a function of these to be imparted to the~~ connecting faces ~~to be assembled~~.

13. (Currently amended) ~~The Method~~ method according to ~~any one of~~ claims claim 1 to 12 of producing a complex structure, characterized in that, wherein applying mechanical forces ~~are applied~~ comprises applying mechanical forces to at least one of the substrates by means of a preform ~~consisting of~~ comprising a mold.

14. (Currently amended) ~~The Method~~ method according to claim 13 of producing a complex structure, characterized in that said, wherein the preform ~~consists of~~ comprises a porous mold.

15. (Currently amended) ~~The Method~~ method according to ~~any one of~~ claims claim 1, to 12 of producing a complex structure, characterized in that wherein applying mechanical forces ~~are applied~~ comprises applying mechanical forces to the two substrates ~~with the aid of~~ using at least one deformable preform.

16. (Currently amended) ~~The Method~~ method according to ~~any one of~~ claims claim 1, ~~to 15 of producing a complex structure, characterized in that the,~~ wherein assembling the two substrates ~~are assembled by~~ comprises molecular bonding.

17. (Currently amended) ~~The Method~~ method according to ~~any one of~~ claims claim 1 ~~to 15 of producing a complex structure, characterized in that further~~ comprising treating the two connecting faces ~~to be assembled are treated to~~ facilitate bonding.

18. (Currently amended) ~~The Method~~ method according to ~~any one of~~ claims claim 1 ~~to 17 of producing a complex structure, characterized in that, wherein~~ the two substrates are assembled by direct contact, wherein the surface face of at least one of ~~these the two~~ substrates ~~being is~~ adapted to prevent air from being trapped between the ~~assembled surfaces~~ connecting faces.

19. (Currently amended) ~~The Method~~ method according to claim 18 of ~~producing a complex structure, characterized in that~~ further comprising piercing at least one of the two substrates ~~is pierced~~.

20. (Currently amended) ~~The Method~~ method according to claim 19, of ~~producing a complex structure, characterized in that said substrate is pierced~~ wherein piercing at least one of the two substrates comprises piercing the substrate at its center.

21. (Currently amended) ~~The Method~~ method according to claim 18 of ~~producing a complex structure, characterized~~ further comprising forming in that at least one of the two substrates ~~includes~~ at least one dead-end channel discharging at the edge of the substrate.

22. (Currently amended) ~~The Method~~ method according to ~~any one of~~ claims claim 1, ~~to 15 of producing a complex structure, characterized in that~~ wherein the two substrates are assembled by means of a flow layer.

23. (Currently amended) ~~The Method~~ method according to ~~any one of~~ claims claim 1, to 22 of producing a complex structure, characterized in that ~~assembly is carried out~~ wherein the two substrates are assembled at a temperature higher than room temperature.

24. (Currently amended) ~~The Method~~ method according to claim 23 of producing a complex structure, characterized in that ~~the substrates are heated~~ further comprising heating the two substrates by contact with heated preforms.

25. (Currently amended) ~~A Method~~ method according to claim 24, of producing a complex structure, characterized in that wherein the preforms are heated to respective different temperatures.

26. ~~A Method~~ method for transferring a thin layer from a source substrate to a target substrate, comprising the following steps:

[[~~-~~]] ionically implanting the source substrate through ~~one~~ a face thereof to create a buried weakened layer at a particular depth relative to the ~~implanted~~ face of the source substrate, a thin layer thereby being delimited between the ~~implanted~~ face and the buried weakened layer;

curving each of the source substrate and the target substrate by applying mechanical forces to create a tangential stress state difference between the face of the source substrate and a face of the target substrate;

[[~~-~~]] assembling ~~one~~ the face of the source substrate to ~~one~~ the face of the target substrate to form an assembled structure; and

[[~~-~~]] dissociating the thin layer from ~~the~~ a remainder of the source substrate ~~in the buried layer,~~

~~characterized in that, prior to assembly, a tangential stress state difference is created between the two faces to be assembled by curving each of the two substrates to be assembled by applying mechanical forces, this difference being selected to obtain within the assembled structure a predetermined stress state at the moment of dissociation~~

wherein the tangential stress state difference is selected to produce a predetermined stress state within the assembled structure at the moment of dissociation.

27. ~~The Method~~ method according to claim 26 ~~of transferring a thin layer,~~
~~characterized in that the,~~ wherein creating a tangential stress state difference between
the two faces ~~to be assembled is selected~~ comprises creating a tangential stress state
difference to minimize the internal stresses at the moment of dissociation.